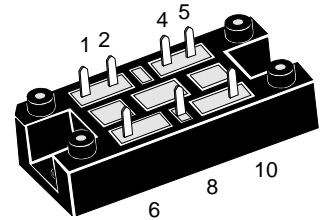
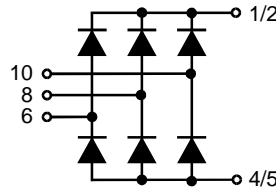


# Three Phase Rectifier Bridge

**$I_{dAVM} = 25 \text{ A}$**   
 **$V_{RRM} = 800-1800 \text{ V}$**

$V_{RSM}$ V	$V_{RRM}$ V	Type
900	800	VUO 22-08NO1
1300	1200	VUO 22-12NO1
1500	1400	VUO 22-14NO1
1700	1600	VUO 22-16NO1
1900	1800	VUO 22-18NO1



Symbol	Test Conditions	Maximum Ratings	
$I_{dAV}$	$T_K = 90^\circ\text{C}$ , module	22	A
$I_{dAV}$	$T_A = 45^\circ\text{C}$ ( $R_{thKA} = 0.5 \text{ K/W}$ ), module	25	A
$I_{dAVM}$	module	25	A
$I_{FSM}$	$T_{VJ} = 45^\circ\text{C}$ ; $V_R = 0$	$t = 10 \text{ ms}$ (50 Hz), sine	100 A
		$t = 8.3 \text{ ms}$ (60 Hz), sine	106 A
	$T_{VJ} = T_{VJM}$ $V_R = 0$	$t = 10 \text{ ms}$ (50 Hz), sine	85 A
		$t = 8.3 \text{ ms}$ (60 Hz), sine	90 A
$I^2t$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	$t = 10 \text{ ms}$ (50 Hz), sine	50 A <sup>2</sup> s
		$t = 8.3 \text{ ms}$ (60 Hz), sine	47 A <sup>2</sup> s
	$T_{VJ} = T_{VJM}$ $V_R = 0$	$t = 10 \text{ ms}$ (50 Hz), sine	36 A <sup>2</sup> s
		$t = 8.3 \text{ ms}$ (60 Hz), sine	33 A <sup>2</sup> s
$T_{VJ}$		-40...+130	°C
$T_{VJM}$		130	°C
$T_{stg}$		-40...+125	°C
$V_{ISOL}$	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	$t = 1 \text{ min}$	3000 V~
		$t = 1 \text{ s}$	3600 V~
$M_d$	Mounting torque (M5) (10-32UNF)	2 - 2.5	Nm
		18-22	lb.in.
Weight	typ.	35	g

### Features

- Package with DCB ceramic base plate
- Isolation voltage 3600 V~
- Planar passivated chips
- Blocking voltage up to 1800 V
- Low forward voltage drop
- Leads suitable for PC board soldering
- UL registered E72873

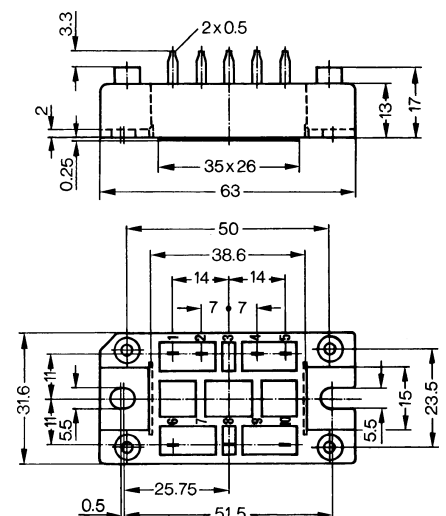
### Applications

- Supplies for DC power equipment
- Input rectifiers for PWM inverter
- Battery DC power supplies
- Field supply for DC motors

### Advantages

- Easy to mount with two screws
- Space and weight savings
- Improved temperature and power cycling

### Dimensions in mm (1 mm = 0.0394")



Data according to IEC 60747 and refer to a single diode unless otherwise stated. IXYS reserves the right to change limits, test conditions and dimensions.

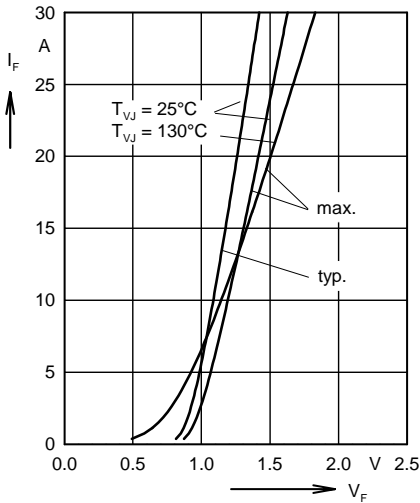


Fig. 1 Forward current versus voltage drop per diode

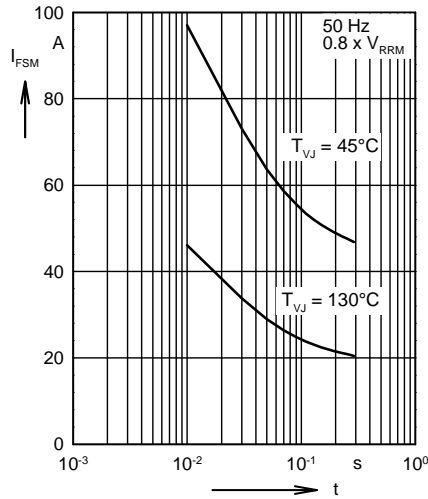


Fig. 2 Surge overload current per diode  
 $I_{FSM}$ : Crest value.  $t$ : duration

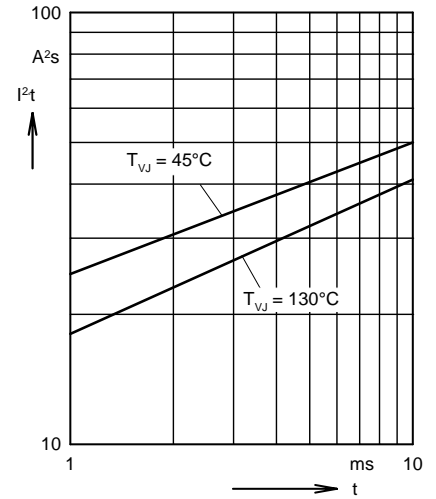


Fig. 3  $I^2t$  versus time (1-10 ms) per diode

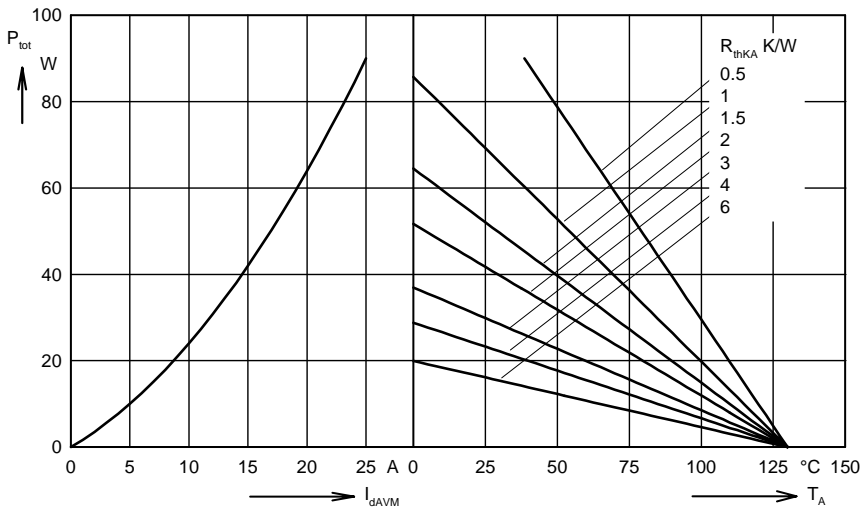


Fig. 4 Power dissipation versus direct output current and ambient temperature

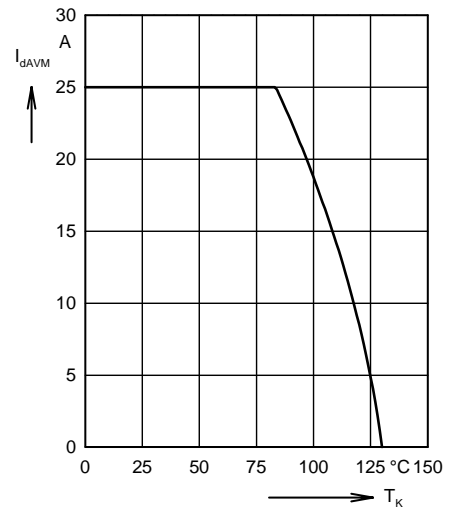


Fig. 5 Maximum forward current at heatsink temperature  $T_K$

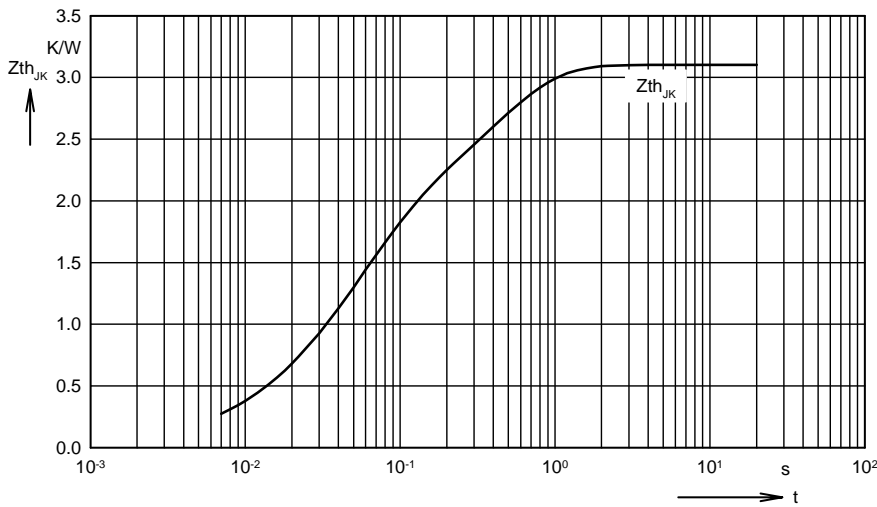


Fig. 6 Transient thermal impedance junction to heatsink per diode

Constants for  $Z_{thJK}$  calculation:

i	$R_{th}$ (K/W)	$t_i$ (s)
1	0.015	0.008
2	0.1	0.02
3	1.635	0.05
4	1.35	0.4